VT930
3U Rugged MTCA.1 Chassis Platform with 12 AMC Slots

Key Features

- Rugged MTCA.1 sub-rack 19” x 3U x 8.35” deep
- Up to 12 AMCs: 6 full-size and 6 mid-size
- Designed for external forced air cooling (bottom to top)
- Full redundancy with dual MicroTCA Carrier Hub (MCH) and Power Modules
- Provision for local airflow management
- No active components on the backplane
- ESD jack at the top front

Benefits

- Rugged design for Mil/Aero, Industrial, and Transportation applications with 40GbE capable
- Scorpionware™ Shelf Management Software included at no additional cost
- Design utilizes proven VadaTech subcomponents and engineering techniques
- Full system supply from industry leader
- AS9100 and ISO9001 certified company
VT930

The VT930 is a 3U MTCA chassis with 12 AMC slots that can accept any AMC.1, AMC.2, AMC.3 and/or AMC.4. The chassis has perforated bottom and top covers for airflow from an external fan tray (fans not included).

The chassis is designed to MicroTCA.1 specification for rugged applications. It has a Dual Star backplane configuration and is 40GbE capable.

FRU Information and Carrier Locator

The VT930 has dual redundant FRU information and Carrier Locator. The Carrier Locator is assigned by the easily accessible mechanical dip switches. As the switches are removable, the backplane can remain passive. The MCH reads the Locator via its private I2C bus.

40G Backplane

The VT930 is a 40GbE passive backplane that does not have any active components, making serviceability straightforward.

Scorpionware™ Software

VadaTech’s Scorpionware software can be used to access information about the current state of the Shelf or the Carrier, obtain information such as the FRU population, or monitor alarms, power management, current sensor values, and the overall health of the Shelf. The software GUI is very powerful, providing a Virtual Carrier and FRU construct for a simple, effective interface.

Figure 1: VT819 Chassis
Chassis Layout

Key:
PM: Power Module
MCH: Micro TCA Carrier Hub
AMC: Advanced Mezzanine Card
FS: Full-size
MS: Mid-size

Figure 2: VT930 Chassis Front View

Backplane Connections

Figure 3: VT930 Backplane Connections
Specifications

| Architecture | Dimensions | Width: 19”
| | Depth: 8.35”
| | Height: 3U
| Type | MTCA Chassis | 12 AMC.0 single module, (6 mid-size and 6 full size)
| Standards | AMC Type | AMC.0, AMC.1, AMC.2, AMC.3 and AMC.4
| | MTCA Type | MicroTCA.1
| Configuration | Power | VT930 Dependent on Power Module used
| Environmental Temperature | Operating temperature: –20° to +70° C
| | Storage Temperature: –40° to +70°C
| Altitude | 10,000 ft operating
| | 40,000 ft non-operating
| Other | Relative Humidity | 5 to 95% non-condensing
| MTBF | MIL Hand book 217-F@ TBD hrs
| Certifications | Designed to meet FCC, CE and UL certifications, where applicable
| Standards | VadaTech is certified to both the ISO9001:2000 and AS9100B:2004 standards
| Warranty | One (1) year, see VadaTech Terms and Conditions

INTEGRATION SERVICES AND APPLICATION-READY PLATFORMS

VadaTech has a full ecosystem of OpenVPX, ATCA and MTCA products including chassis platforms, shelf managers, AMC modules, Switch and Payload Boards, Rear Transition Modules (RTMs), Power Modules, and more. The company also offers integration services as well as pre-configured Application-Ready Platforms. Please contact VadaTech Sales for more information.
Ordering Options

VT930 – 0BC-000-00J

<table>
<thead>
<tr>
<th>B = Ports 2 and 3</th>
<th>C = MCH CLK3 Channels</th>
<th>J = Conformal Coating</th>
</tr>
</thead>
<tbody>
<tr>
<td>1 = Direct connections</td>
<td>1 = Non-redundant (Telco)</td>
<td>0 = No coating</td>
</tr>
<tr>
<td>2 = To MCH</td>
<td>2 = Non-redundant (FCLKA)</td>
<td>1 = Humiseal 1A33 Polyurethane</td>
</tr>
<tr>
<td></td>
<td>3 = Redundant</td>
<td>2 = Humiseal 1B31 Acrylic</td>
</tr>
</tbody>
</table>

Related Products

AMC515
- AMC FPGA carrier for FPGA Mezzanine Card (FMC) per VITA 57
- Xilinx Virtex-7 XC7V2000T in 1925 package
- AMC Ports 4-11 are routed to FPGA (protocols such as PCIe, SRIO, XAUI, etc. are FPGA programmable)

AMC720
- Intel® Xeon™ E3 processor AMC
- Conduction cooled version available
- PCIe Gen2 (Gen3 on v2 option)

UTC020
- Single module, full-size per AMC.0
- Dual -36V DC to -75V DC input, 936W (available in 468W)
- Hot swappable with support for power module redundancy
Choose VadaTech

We are technology leaders
• First-to-market silicon
• Constant innovation
• Open systems expertise

We commit to our customers
• Partnerships power innovation
• Collaborative approach
• Mutual success

We deliver complexity
• Complete signal chain
• System management
• Configurable solutions

We manufacture in-house
• Agile production
• Accelerated deployment
• AS9100 accredited

Trademarks and Disclaimer
The VadaTech logo is a registered trademark of VadaTech, Inc. Other registered trademarks are the property of their respective owners. AdvancedTCA™ and the AdvancedMC™ logo are trademarks of the PCI Industrial Computers Manufacturers Group. All rights reserved. Specification subject to change without notice.

© 2019 VadaTech Incorporated. All rights reserved.